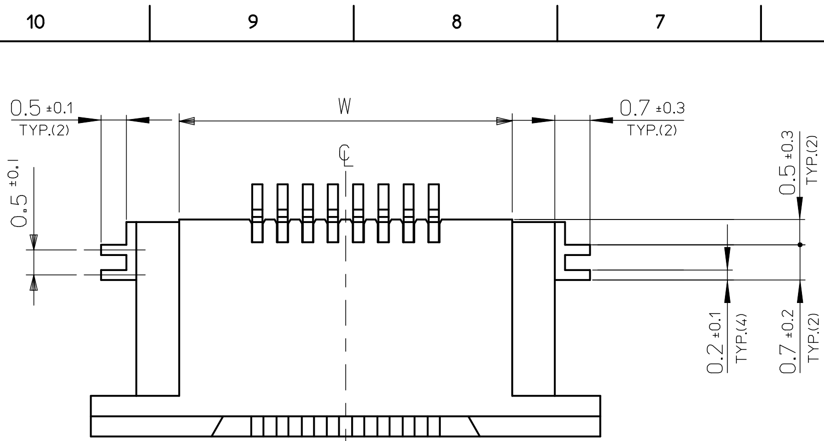

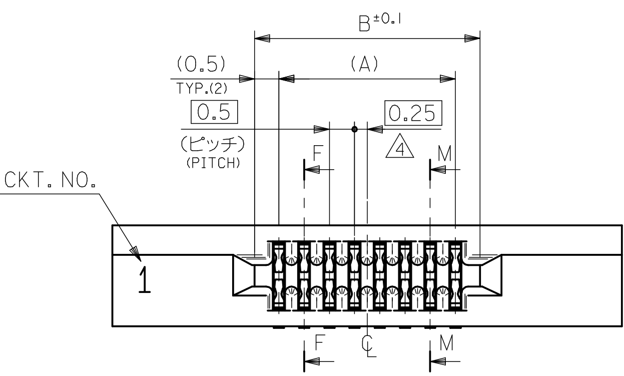

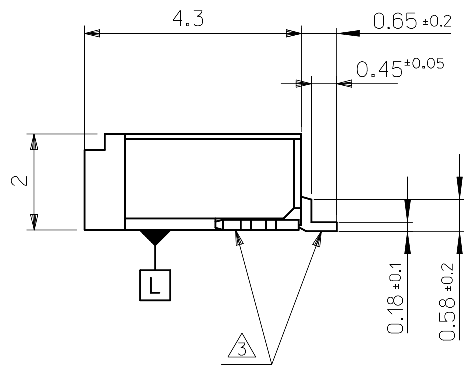

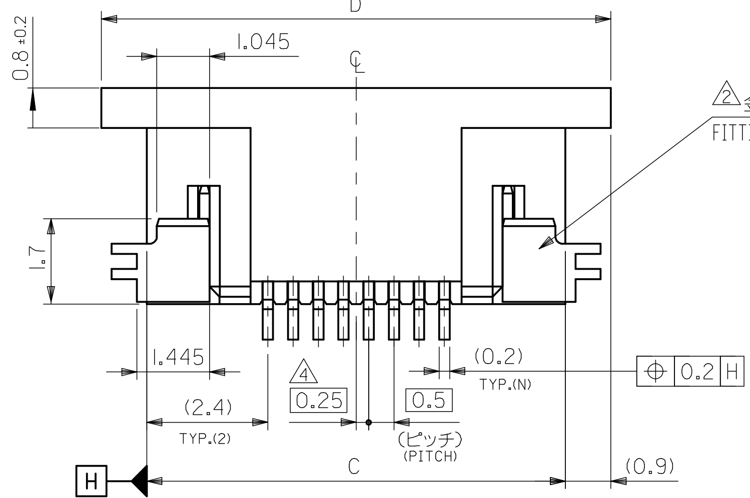

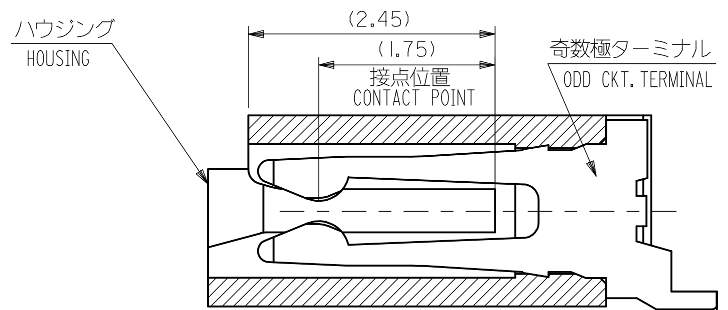

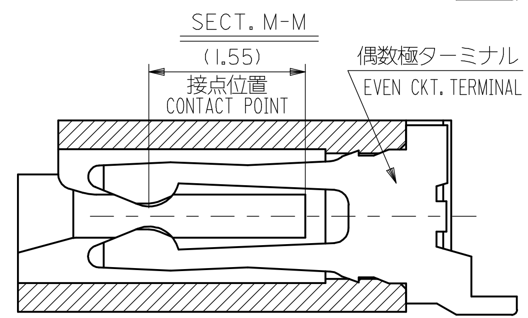

注記(NOTES)

1. 使用材料(MATERIAL)
   ターミナル(TERMINAL):リン青銅
   PHOSPHOR BRONZE t=0.2
   錫ビスマスメッキ 1.0マイクロメートル以上
   TIN-BISMUTH 1.0 MICROMETER MINIMUM
   ニッケル下地 1.0マイクロメートル以上
   NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
   ハウジング(HOUSING):46ナイロン(46NYLON), UL94V-0
   金具(FITTING NAIL):リン青銅
   PHOSPHOR BRONZE t=0.2
   錫メッキ 1.0マイクロメートル以上
   TIN 1.0 MICROMETER MINIMUM
   ニッケル下地 1.0マイクロメートル以上
   NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM

△2

△3 パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)
ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向0.1MAX.下方向0.15MAX.とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
△4 UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)

5. 本製品は 52689-**40 の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE 52689-**40.

MODEL NO.	52689-**49

REV	DESCRIPTION
G	REVISED EC NO: J2017-0300 2016/12/01 DRWN:GES CH'KD: APPR:MSASAO 2016/12/20

GENERAL TOLERANCES (UNLESS SPECIFIED)

~~0.25~~	UNDER		UNDER	±
~~0.25~~	OVER	~~0.5~~	UNDER	±
~~0.5~~	OVER	~~1.0~~	UNDER	±
0	OVER	10	UNDER	± 0.2
10	OVER	30	UNDER	± 0.25
30	OVER			± 0.3
ANGULAR		±3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	---	METRIC	THIRD ANGLE PROJECTION

DRAWN BY	DATE
H.KAWABATA	'04/02/03
CHECKED BY	DATE
K.TOJO	'04/02/03
APPROVED BY	DATE
M.SASAO	'04/02/03
MATERIAL NO.	
SEE SHEET 2	

TITLE
0.5 FPC CONN NON ZIF
HSG ASSY FOR SMT(R/A)
-LEAD FREE-

molex

DOCUMENT NO.	SHEET NO.
SD-52689-034	1 OF 2

SIZE A3

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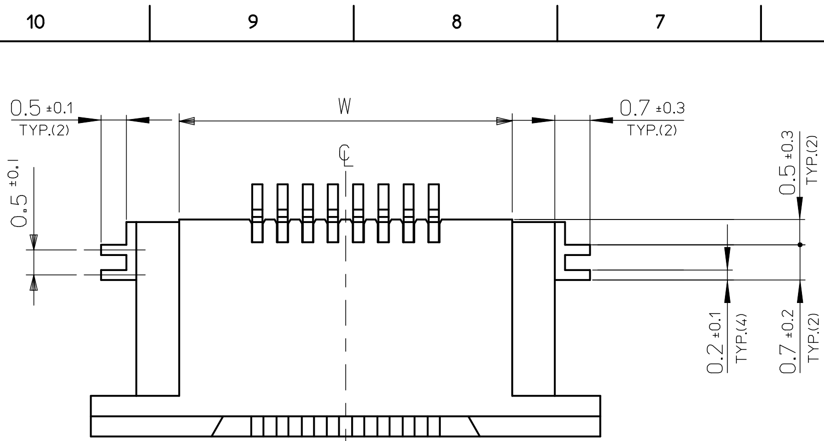

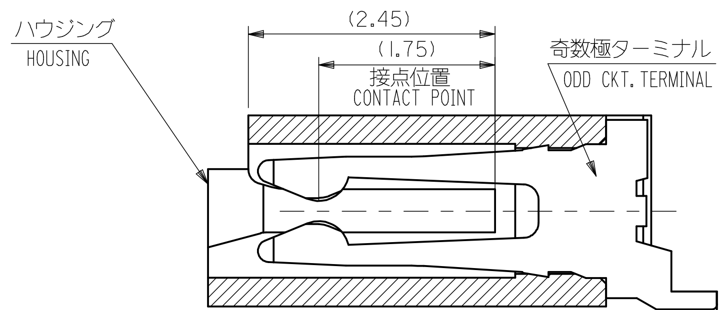

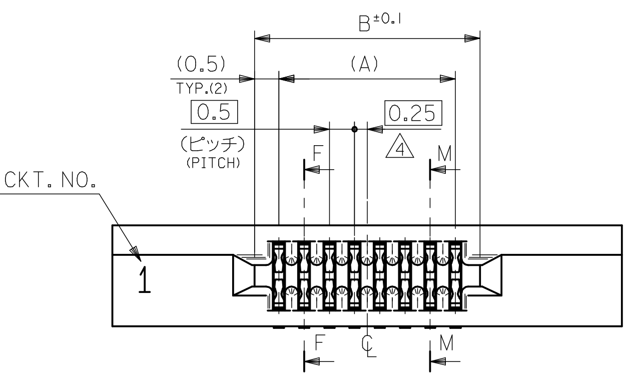

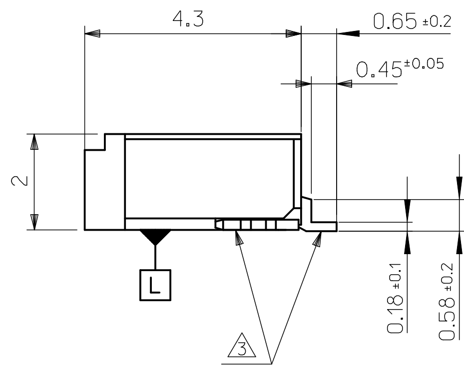

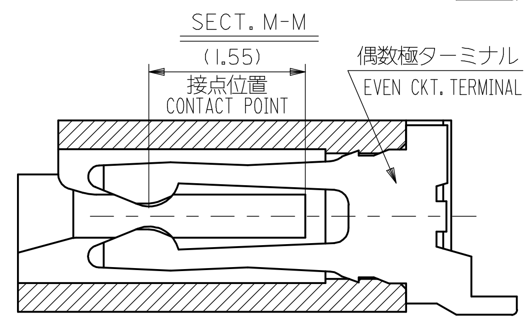

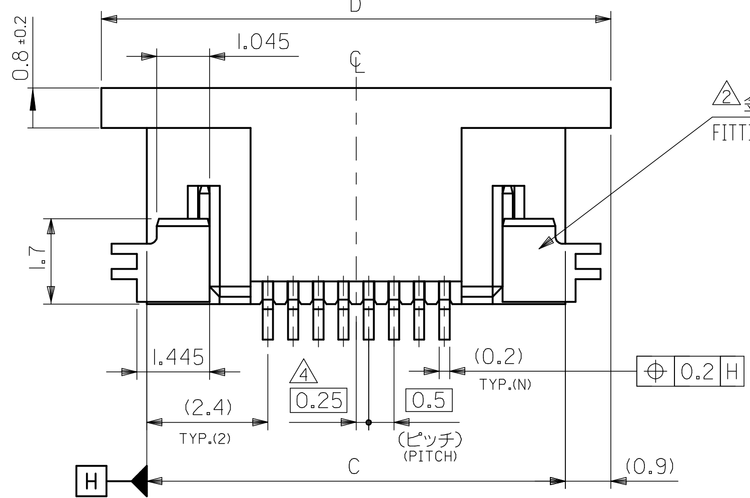

注記(NOTES)

1. 使用材料(MATERIAL)
   ターミナル(TERMINAL):リン青銅
   PHOSPHOR BRONZE t=0.2
   錫ビスマスメッキ　1.0マイクロメートル以上
   TIN-BISMUTH 1.0 MICROMETER MINIMUM
   ニッケル下地　1.0マイクロメートル以上
   NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
   ハウジング(HOUSING):46ナイロン(46NYLON), UL94V-0
   金具(FITTING NAIL):リン青銅
   PHOSPHOR BRONZE t=0.2
   錫メッキ　1.0マイクロメートル以上
   TIN 1.0 MICROMETER MINIMUM
   ニッケル下地　1.0マイクロメートル以上
   NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM

2.

3. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)
   ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向0.1MAX.下方向0.15MAX.とする。
   MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.

4. 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)

5. 本製品は 52689-**40 の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE 52689-**40.

MODEL NO.	52689-**49

REVISED	
EC NO: J2017-0300	2016/12/01
DRWN: GES	2016/12/20
CH'KD:	
APPR: MSASAO	
REV	G

GENERAL TOLERANCES (UNLESS SPECIFIED)

0.25	UNDER		UNDER	±
0.25	OVER	0.5	UNDER	±
0.5	OVER	1.0	UNDER	±
0	OVER	10	UNDER	± 0.2
10	OVER	30	UNDER	± 0.25
30	OVER			± 0.3
ANGULAR	±3 °			

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	---	METRIC	THIRD ANGLE PROJECTION

DRAWN BY: H.KAWABATA	DATE: '04/02/03	TITLE: 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-
CHECKED BY: K.TOJO	DATE: '04/02/03	
APPROVED BY: M.SASAO	DATE: '04/02/03	molex
MATERIAL NO.: SEE SHEET 2	DOCUMENT NO.: SD-52689-034	SHEET NO.: 1 OF 2
SIZE: A3		

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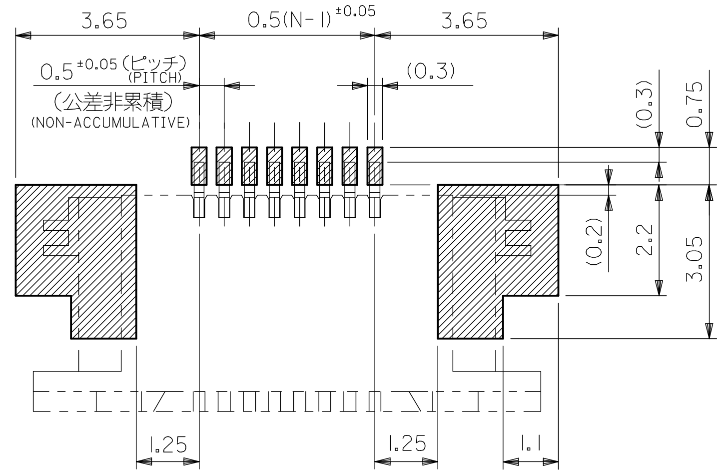
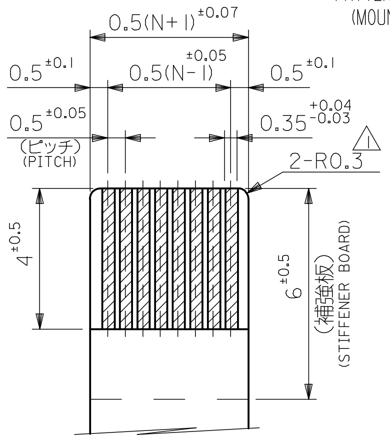


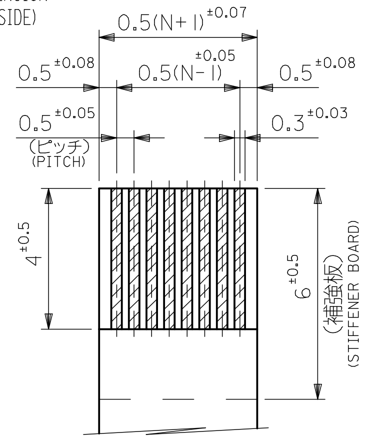
参考基板レイアウト（マウント面）
REFERENCE P.C.BOARD PATTERN DIMENSION (MOUNTING SIDE)

注記 NOTES

⚠ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.



適合ＦＰＣ推奨寸法
APPLICABLE FPC RECOMMENDED DIMENSION
(仕上がり厚さ：0.3±0.03)
(THICKNESS:0.3±0.03)



適合ＦＦＣ推奨寸法
APPLICABLE FFC RECOMMENDED DIMENSION
(仕上がり厚さ：0.3±0.03)
(THICKNESS:0.3±0.03)

ＦＰＣについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

MODEL NO. 52689-**49	W	D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	極数 CKT.
	17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
	13.6	17.1	15.3	11.5	10.5	52689-2287	52689-2249	22

REVISED: G — EC NO: J2017-0300, DRWN:GES 2016/12/01, CH'KD:, APPR:MSASAO 2016/12/20

GENERAL TOLERANCES (UNLESS SPECIFIED)

~~0.25~~		UNDER		~~±~~
~~0.25~~	OVER	~~0.5~~	UNDER	~~±~~
~~0.5~~	OVER	~~1.0~~	UNDER	~~±~~
0	OVER	10	UNDER	±0.2
10	OVER	30	UNDER	±0.25
30	OVER			±0.3
ANGULAR	±3°			

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY | SCALE: --- | DESIGN UNITS: METRIC | THIRD ANGLE PROJECTION

DRAWN BY	H.KAWABATA	DATE '04/02/03
CHECKED BY	K.TOJO	DATE '04/02/03
APPROVED BY	M.SASAO	DATE '04/02/03

TITLE: 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-

molex

MATERIAL NO.: SEE TABLE

DOCUMENT NO.: SD-52689-034

SHEET NO.: 2 OF 2

SIZE: A3

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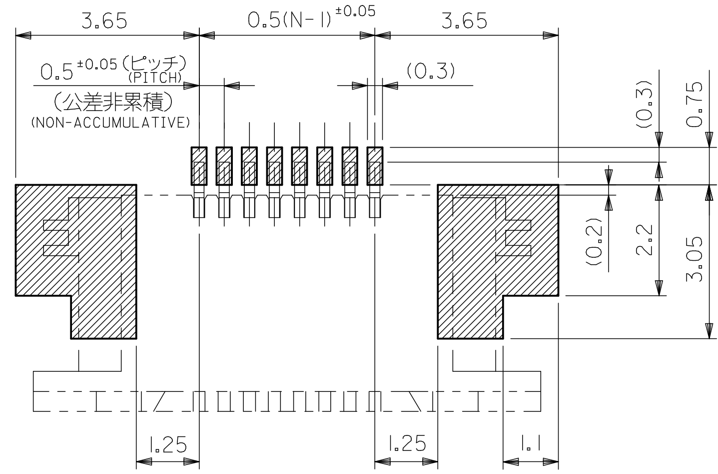
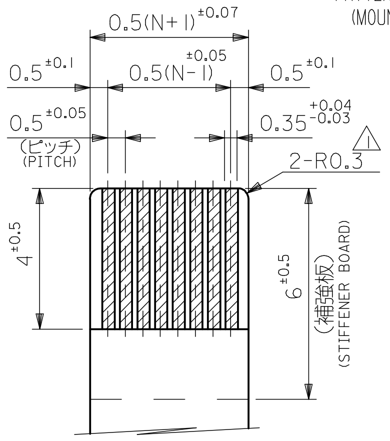


参考基板レイアウト
(マウント面)

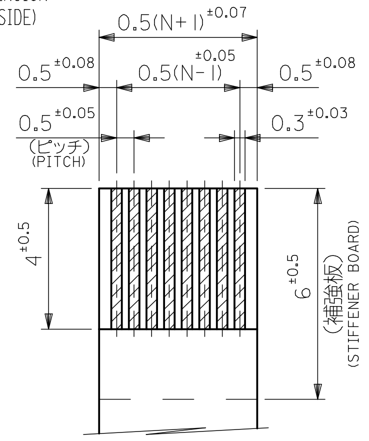
REFERENCE P.C.BOARD
PATTERN DIMENSION
(MOUNTING SIDE)

注記 NOTES

⚠ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ：0.3±0.03)
(THICKNESS:0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ：0.3±0.03)
(THICKNESS:0.3±0.03)

FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

52689-**49 MODEL NO.	W	D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	極数 CKT.
	17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
	13.6	17.1	15.3	11.5	10.5	52689-2287	52689-2249	22

REVISED
G
EC NO: J2017-0300 2016/12/01
DRWN:GES
CH'KD:
APPR:MSASAO 2016/12/20
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)

~~0.25~~	~~UNDER~~		~~UNDER~~	~~±~~
~~0.25~~	~~OVER~~	~~0.5~~	~~UNDER~~	~~±~~
~~0.5~~	~~OVER~~	~~1.0~~	~~UNDER~~	~~±~~
0	OVER	10	UNDER	±0.2
10	OVER	30	UNDER	±0.25
30	OVER			±0.3
ANGULAR	±3 °			

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY	DATE
H.KAWABATA	'04/02/03
CHECKED BY	DATE
K.TOJO	'04/02/03
APPROVED BY	DATE
M.SASAO	'04/02/03

TITLE
0.5 FPC CONN NON ZIF
HSG ASSY FOR SMT(R/A)
-LEAD FREE-

molex

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-52689-034
SHEET NO.: 2 OF 2
SIZE: A3

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